

MOSFET – Power, Single, N-Channel, μ 8FL

30 V, 164 A

NTTFS4C02N

Features

- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- ESD Protection Level: CDM > 1 kV
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- DC-DC Converters
- Power Load Switch
- Notebook Battery Management

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

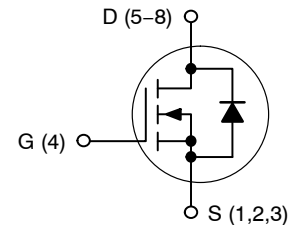
Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	30	V
Gate-to-Source Voltage			V_{GS}	± 20	V
Continuous Drain Current $R_{\theta JA}$ (Note 1)	Steady State	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	25	A
		$T_A = 85\text{ }^{\circ}\text{C}$		21	
Power Dissipation $R_{\theta JA}$ (Note 1)		$T_A = 25\text{ }^{\circ}\text{C}$	P_D	2.5	W
Continuous Drain Current $R_{\theta JA} \leq 10\text{ s}$ (Note 1)		$T_A = 25\text{ }^{\circ}\text{C}$	I_D	35	A
		$T_A = 85\text{ }^{\circ}\text{C}$		27	
Power Dissipation $R_{\theta JA} \leq 10\text{ s}$ (Note 1)		$T_A = 25\text{ }^{\circ}\text{C}$	P_D	5	W
Continuous Drain Current $R_{\theta JA}$ (Note 2)		$T_A = 25\text{ }^{\circ}\text{C}$	I_D	15	A
		$T_A = 85\text{ }^{\circ}\text{C}$		12	
Power Dissipation $R_{\theta JA}$ (Note 2)		$T_A = 25\text{ }^{\circ}\text{C}$	P_D	1	W
Continuous Drain Current $R_{\theta JC}$ (Note 1)		$T_C = 25\text{ }^{\circ}\text{C}$	I_D	164	A
	$T_C = 85\text{ }^{\circ}\text{C}$	127			
Power Dissipation $R_{\theta JC}$ (Note 1)	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	107	W	
Pulsed Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$, $t_p = 10\text{ }\mu\text{s}$	I_{DM}	663	A	
Operating Junction and Storage Temperature Range			T_J , T_{stg}	-55 to +175	$^{\circ}\text{C}$
Source Current (Body Diode)			I_S	97	A
Drain to Source dV/dt			dV/dt	6.0	V/ns
Single Pulse Drain-to-Source Avalanche Energy ($I_L = 37\text{ A}_{pk}$) (Note 3)			E_{AS}	162	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	$^{\circ}\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

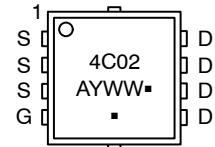
1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
2. Surface-mounted on FR4 board using the minimum recommended pad size.
3. This is the absolute maximum ratings. Parts are 100% tested at $T_J = 25^\circ\text{C}$, $V_{GS} = 10\text{ V}$, $I_L = 36\text{ A}$, $E_{AS} = 65\text{ mJ}$.

$V_{(BR)DSS}$	$R_{DS(on)} \text{ MAX}$	$I_D \text{ MAX}$
30 V	2.25 m Ω @ 10 V	164 A
	3.1 m Ω @ 4.5 V	

N-Channel MOSFET



MARKING DIAGRAM



4C02 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NTTFS4C02NTAG	WDFN-8 (Pb-Free)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	1.4	$^{\circ}\text{C/W}$
Junction-to-Ambient – Steady State (Note 4)	$R_{\theta JA}$	58	
Junction-to-Ambient – Steady State (Note 5)	$R_{\theta JA}$	150	
Junction-to-Ambient – ($t \leq 10$ s) (Note 4)	$R_{\theta JA}$	30	

4. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.

5. Surface-mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$			13.8		mV/ $^{\circ}\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25^{\circ}\text{C}$		1.0	μA
			$T_J = 125^{\circ}\text{C}$		10	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = 30\text{ V}$	$T_J = 25^{\circ}\text{C}$		10	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = 20\text{ V}$			100	nA

ON CHARACTERISTICS (Note 6)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\text{ }\mu\text{A}$	1.3	1.6	2.2	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			5.0		mV/ $^{\circ}\text{C}$
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		1.9	2.25	m Ω
		$V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$		2.7	3.1	
Forward Transconductance	g_{FS}	$V_{DS} = 1.5\text{ V}, I_D = 50\text{ A}$		140		S
Gate Resistance	R_G			0.9		Ω

CHARGES AND CAPACITANCES

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 15\text{ V}$		2980		pF
Output Capacitance	C_{OSS}			1200		
Reverse Transfer Capacitance	C_{RSS}			55		
Output Charge	Q_{OSS}	$V_{GS} = 0\text{ V}, V_{DD} = 15\text{ V}$		25		nC
Capacitance Ratio	C_{RSS}/C_{ISS}	$V_{GS} = 0\text{ V}, V_{DS} = 15\text{ V}, f = 1\text{ MHz}$		0.018		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}; I_D = 50\text{ A}$		20		nC
Threshold Gate Charge	$Q_{G(TH)}$			4.7		
Gate-to-Source Charge	Q_{GS}			8.5		
Gate-to-Drain Charge	Q_{GD}			4		
Gate Plateau Voltage	V_{GP}			2.8		V
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}; I_D = 50\text{ A}$		45		nC

SWITCHING CHARACTERISTICS (Note 7)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 15\text{ V}, I_D = 50\text{ A}, R_G = 3.0\text{ }\Omega$		12		ns
Rise Time	t_r			116		
Turn-Off Delay Time	$t_{d(OFF)}$			25		
Fall Time	t_f			10		

6. Pulse Test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

7. Switching characteristics are independent of operating junction temperatures.

NTTFS4C02N

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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SWITCHING CHARACTERISTICS (Note 7)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V},$ $I_D = 50\text{ A}, R_G = 3.0\text{ }\Omega$		9		ns
Rise Time	t_r			102		
Turn-Off Delay Time	$t_{d(OFF)}$			33		
Fall Time	t_f			6		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 20 A	T _J = 25 °C		0.8	1.1	V
			T _J = 125 °C		0.6		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt = 100 A/μs, I _S = 50 A			42		ns
Charge Time	t _a				21		
Discharge Time	t _b				21		
Reverse Recovery Charge	Q _{RR}				28		nC

6. Pulse Test: pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

7. Switching characteristics are independent of operating junction temperatures.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



TYPICAL CHARACTERISTICS

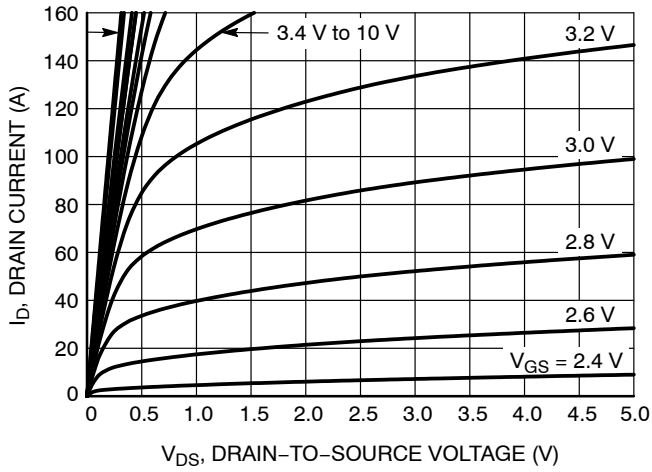


Figure 1. On-Region Characteristics

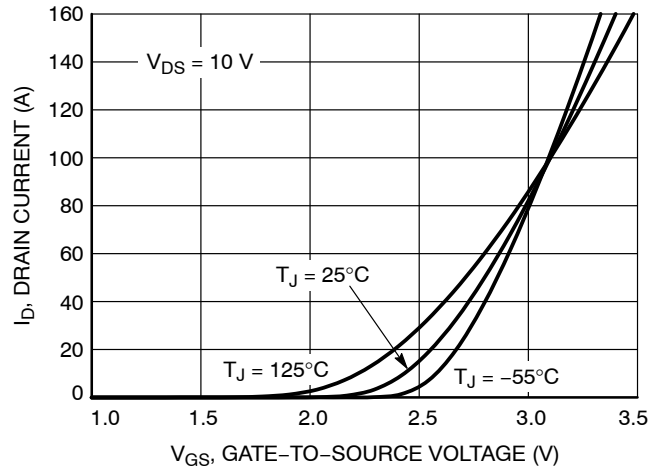


Figure 2. Transfer Characteristics

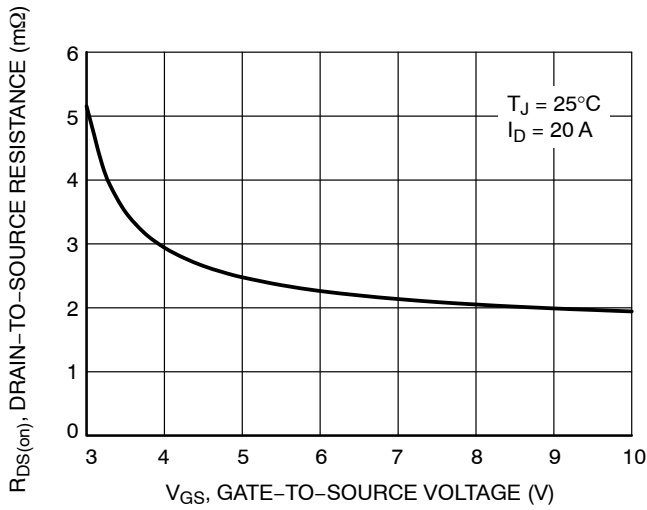


Figure 3. On-Resistance vs. Gate-to-Source Voltage

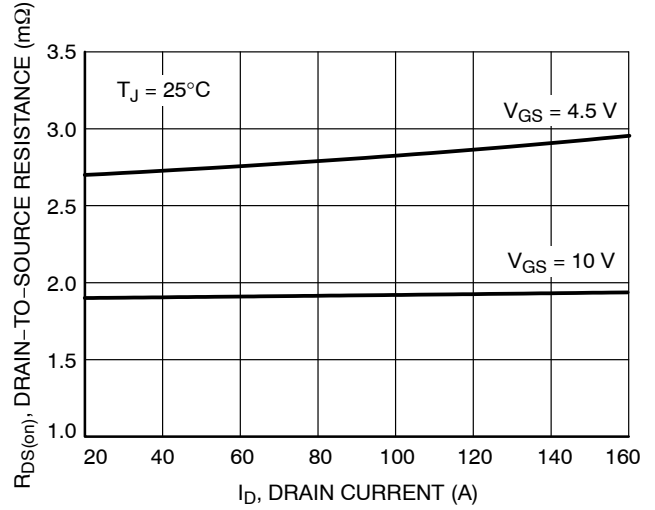


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

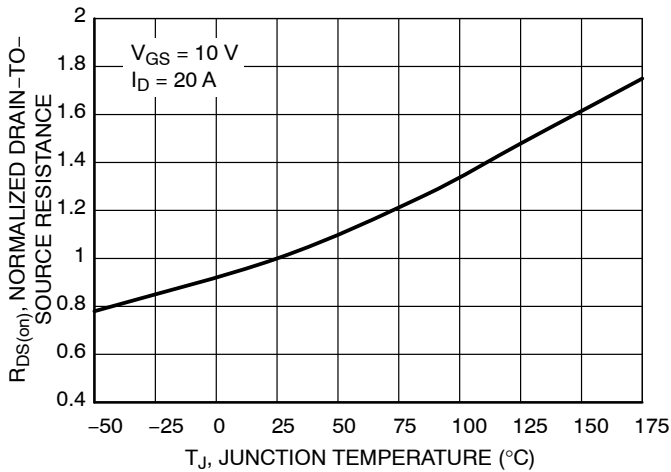


Figure 5. On-Resistance Variation with Temperature

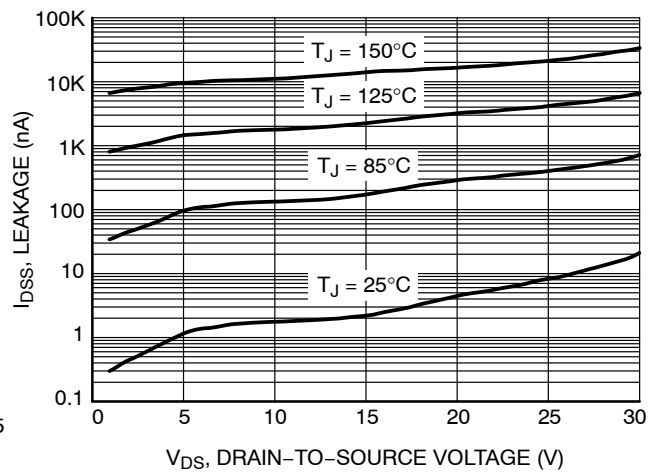


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

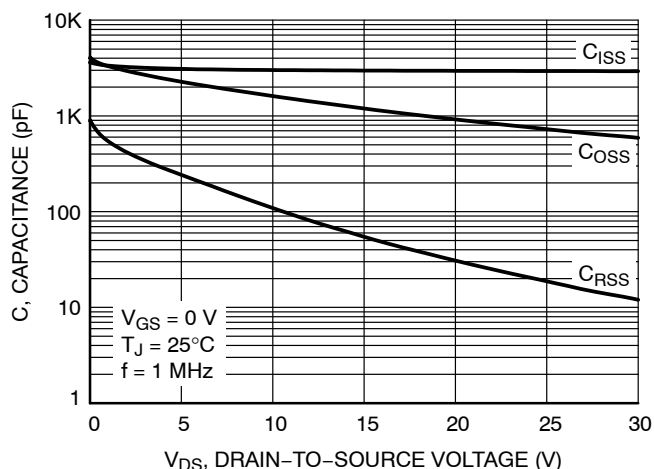


Figure 7. Capacitance Variation

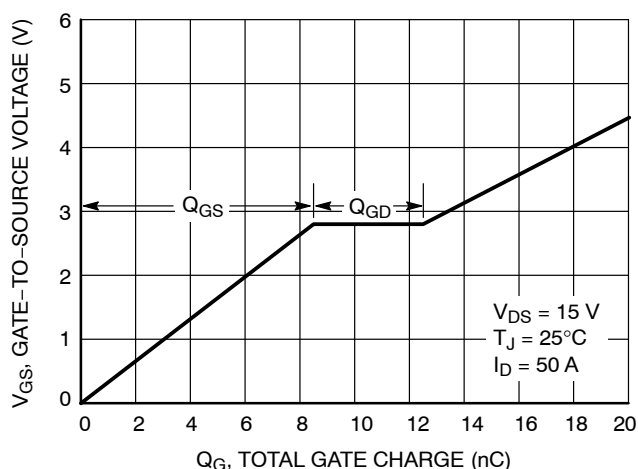


Figure 8. Gate-to-Source vs. Total Charge

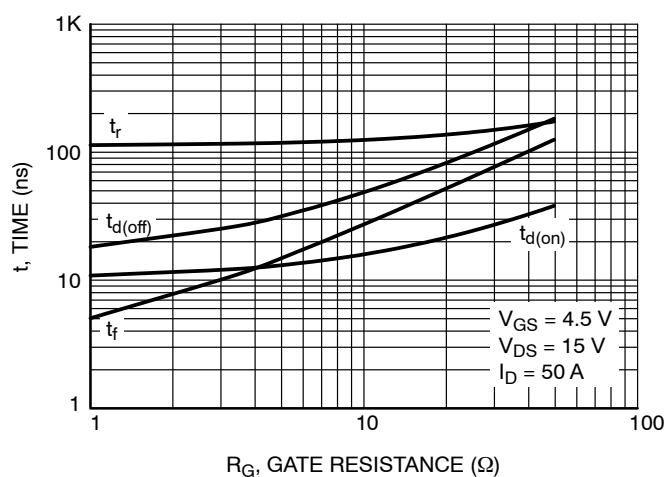


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

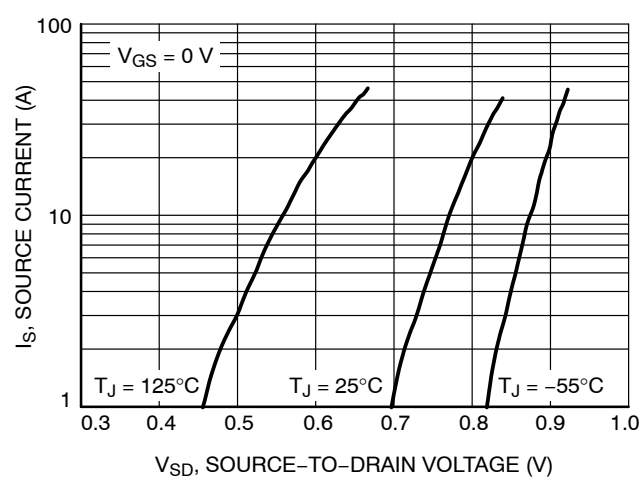


Figure 10. Diode Forward Voltage vs. Current

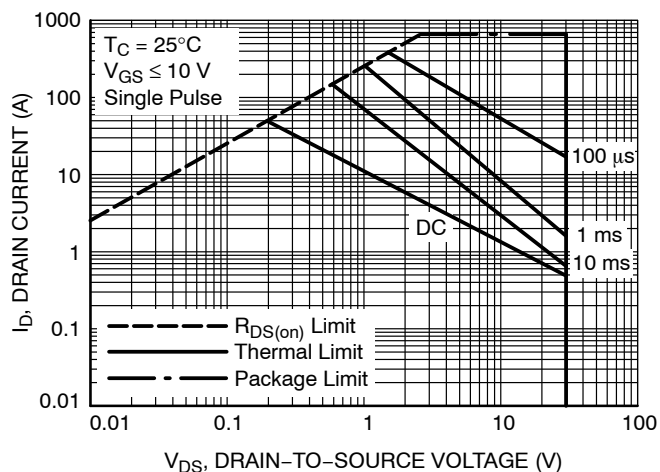


Figure 11. Maximum Rated Forward Biased Safe Operating Area

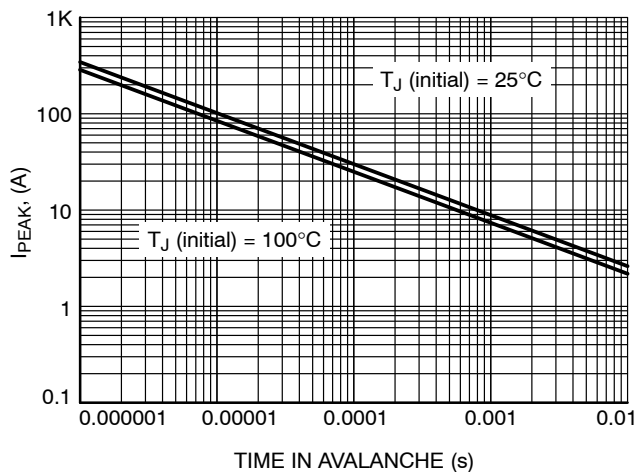


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

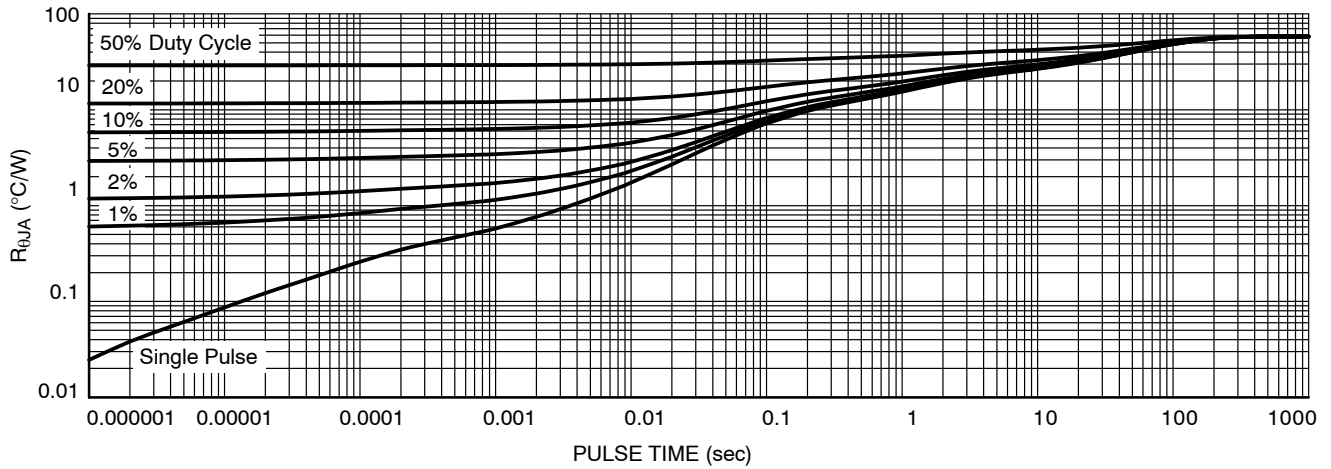


Figure 13. Thermal Characteristics

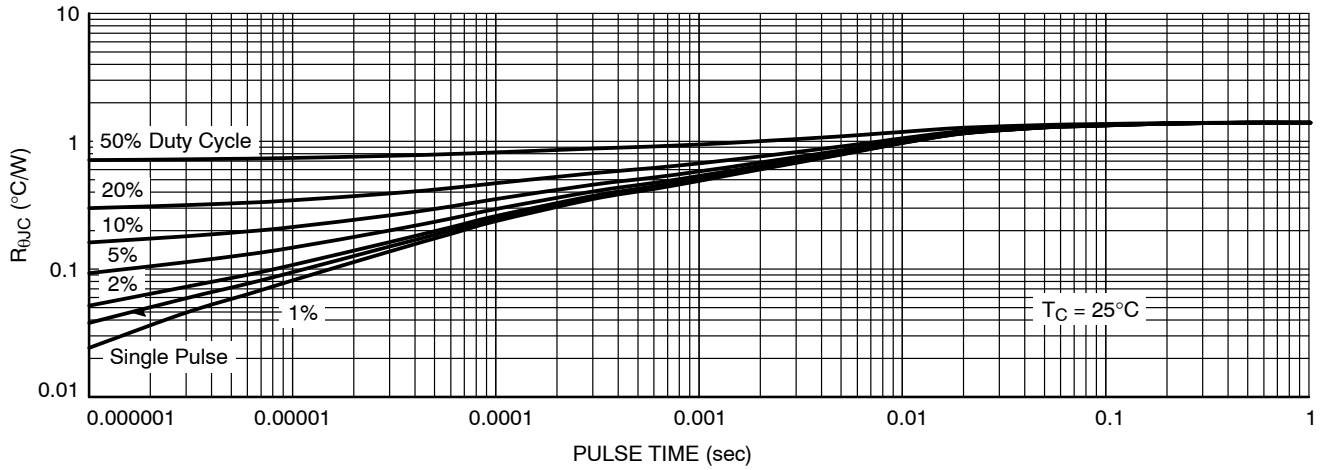


Figure 14. Thermal Characteristics

REVISION HISTORY

Revision	Description of Changes	Date
11	Added new Features bullet.	12/10/2025

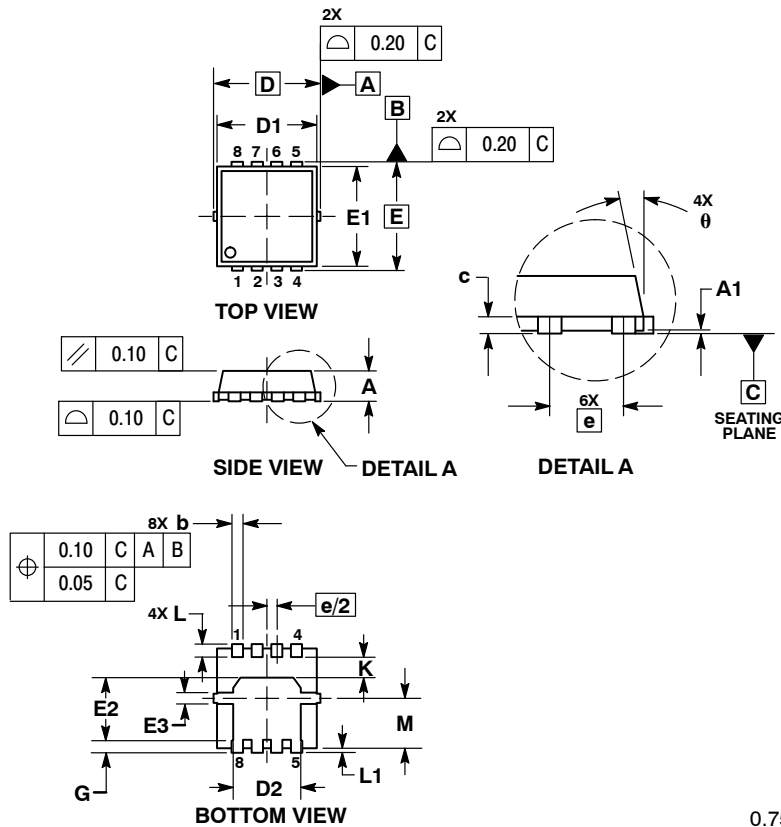
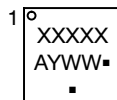
*Please note that this document has been previously updated prior to the inclusion of this revision history table and that the changes tracked only reflect what has occurred on the noted approval dates.



SCALE 2:1

WDFN8 3.3x3.3, 0.65P
CASE 511AB
ISSUE D

DATE 23 APR 2012


GENERIC
MARKING DIAGRAM*


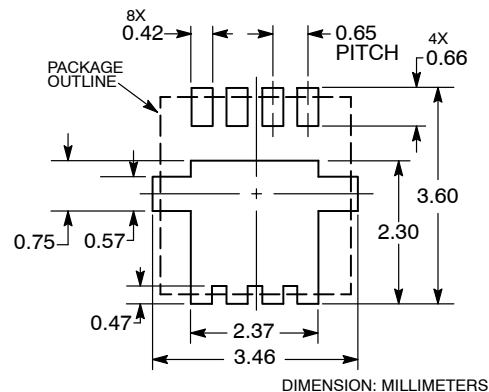
XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	---	0.05	0.000	---	0.002
b	0.23	0.30	0.40	0.009	0.012	0.016
c	0.15	0.20	0.25	0.006	0.008	0.010
D	3.30 BSC			0.130 BSC		
D1	2.95	3.05	3.15	0.116	0.120	0.124
D2	1.98	2.11	2.24	0.078	0.083	0.088
E	3.30 BSC			0.130 BSC		
E1	2.95	3.05	3.15	0.116	0.120	0.124
E2	1.47	1.60	1.73	0.058	0.063	0.068
E3	0.23	0.30	0.40	0.009	0.012	0.016
e	0.65 BSC			0.026 BSC		
G	0.30	0.41	0.51	0.012	0.016	0.020
K	0.65	0.80	0.95	0.026	0.032	0.037
L	0.30	0.43	0.56	0.012	0.017	0.022
L1	0.06	0.13	0.20	0.002	0.005	0.008
M	1.40	1.50	1.60	0.055	0.059	0.063
θ	0 °	---	12 °	0 °	---	12 °

SOLDERING FOOTPRINT*


DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WDFN8 3.3X3.3, 0.65P	PAGE 1 OF 1

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